



General Description

The advanced trench MOS technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and converter applications.

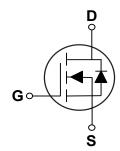
BV _{DSS}	R _{DS(ON)}	I _D
30 V	3.9 mΩ	35 A

Features

- $R_{DS(ON)} \leq 3.9 \text{m} \Omega @V_{GS} = \overline{10V}$
- · Low Gate Charge
- Low R_{DS(ON)}
- · Green Device Available

PPAK3X3 Pin Configuration





Applications

- Power Management in Desktop Computer or DC/DC Converters.
- Isolated DC/DC Converters in Telecom and Industrial.

Absolute Maximum Ratings T_C=25°C unless otherwise noted Symbol **Parameter** Rating Units Drain-Source Voltage V_{DS} 30 ٧ V_{GS} Gate-Source Voltage ±20 V 35 Drain Current - Continuous (T_C=25°C) Α I_D Drain Current - Continuous (T_C=100°C) 32 Α 120 I_{DM} Pulsed Drain Current (NOTE 1) Α **EAS** Single Pulse Avalanche Energy (NOTE 2) 80 mJ IAS 40 Avalanche Current P_D Power Dissipation (NOTE 3) 27 W T_{J} -55 to 150 Operating Junction Temperature Range ٥С Storage Temperature Range -55 to 150 T_{STG} οС Marking Code NC3P9

Thermal Characteristics					
Symbol	Parameter	Тур.	Max.	Unit	
$R_{\theta JA}$	Thermal Resistance Junction to Ambient		60	°C/W	
$R_{\theta JC}$	Thermal Resistance Junction to Case		4.5	°C/W	





Electrical Characteristics (T_{.1}=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V , I_D =250uA	30			V
I _{DSS}	Drain-Source Leakage Current	V_{DS} =30V , V_{GS} =0V , T_J =25 $^{\circ}$ C			1	uA
		V_{DS} =30V , V_{GS} =0V , T_{J} =55 $^{\circ}$ C			5	
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =20A		3.2	3.9	mΩ
		V _{GS} =4.5V , I _D =15A		4.9	6.1	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	1.2	1.7	2.2	V
gfs	Forward Transconductance	V_{DS} =5V , I_{D} =20A		75		S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge			14.7		
Q_{gs}	Gate-Source Charge	V_{DS} =15V , V_{GS} =4.5V , I_{D} =20A		5.8		nC
Q_{gd}	Gate-Drain Charge			3.5		
$T_{d(on)}$	Turn-On Delay Time			7.5		
T _r	Rise Time	V_{DD} =15V , V_{GS} =10V , R_{G} =3 Ω ,		20.2		nS
$T_{d(off)}$	Turn-Off Delay Time	I _D =20A		21.6		113
T_f	Fall Time			4.4		
C _{iss}	Input Capacitance			1476		
C _{oss}	Output Capacitance	V_{DS} =15V , V_{GS} =0V , F=1MHz		556		pF
C _{rss}	Reverse Transfer Capacitance			70		
Rg	Gate resistance	V_{GS} =0V , V_{DS} =0V , F=1MHz		1.65		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current (NOTE 4)	V _G =V _D =0V , Force Current			30	Α
V_{SD}	Diode Forward Voltage (NOTE 1)	V _{GS} =0V , I _S =1A , T _J =25°C			1	V

NOTES:

- 1. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 2. The EAS data shows Max. rating. The test condition is V_{DD} =25V, V_{GS} =10V, I_{AS} =40A, L=0.1mH.
- 3. The power dissipation is limited by 150° C junction temperature.
- 4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.





Characteristics Curves

FIG.1-Typical Output Characteristics

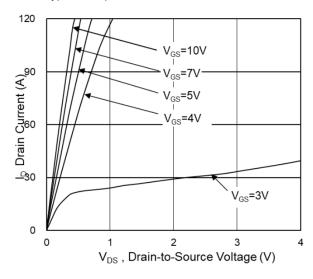


FIG.2-On-Resistance vs. G-S Voltage

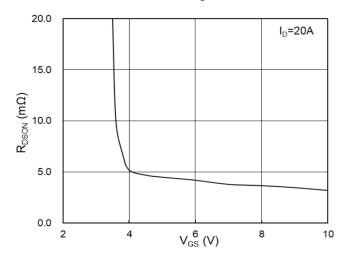


FIG.3-Source Drain Forward Characteristics

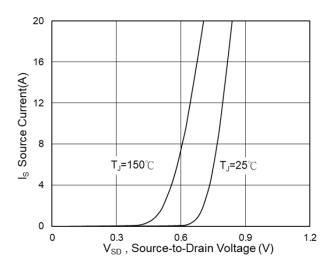


FIG.4-Gate Charge Characteristics

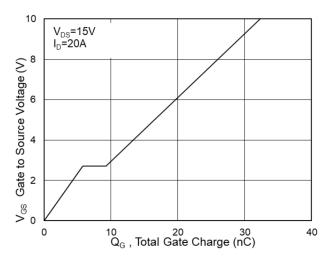


FIG.5-Normalized $V_{GS(th)}$ vs. T_J

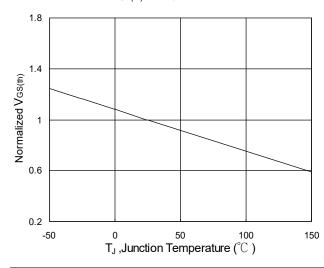
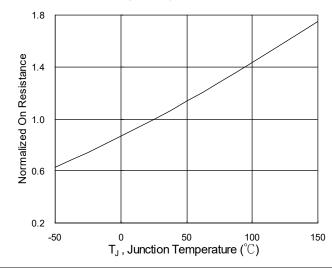


FIG.6-Normalized R_{DSON} vs. T_J







Characteristics Curves

FIG.7-Switching Time Waveform

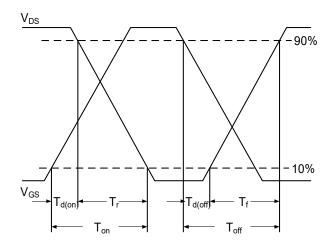
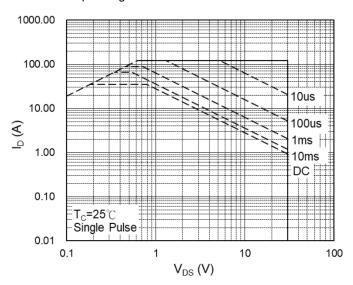
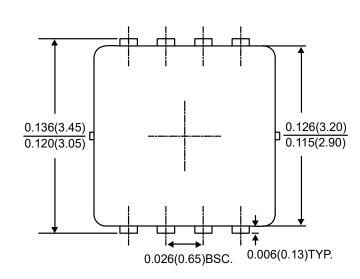
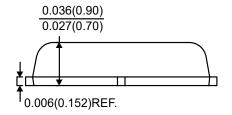


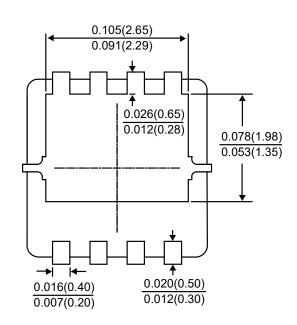
FIG.8-Safe Operating Area

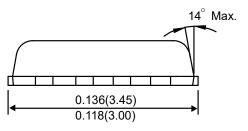


Package Outline Dimensions









PPAK3X3

Dimensions in inches and (millimeters)





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